Contents

SYNTHESIS AND PROPERTIES OF COATINGS USED IN MICROELECTRONIC APPLICATIONS

Thin film barrier layers

Reaction kinetics in tungsten/barrier metal/silicon systems 1
K. Suguro, Y. Nakasaki, T. Inoue, S. Shima and M. Kashiwagi (Kawasaki, Japan)

Reactively sputtered indium oxide diffusion barrier. 15
E. Kolawa, C. W. Nieh, J. M. Molarius, L. Tran, C. Garland, W. Flick, M.-A. Nicolet (Pasadena, CA U.S.A.) and F. C. T. So (San Jose, CA, U.S.A.) and J. C. S. Wei (Santa Clara, CA, U.S.A.)

Al_3Ti formation by diffusion of aluminum through titanium 21
M. Thuillard, L. T. Tran and M.-A. Nicolet (Pasadena, CA, U.S.A.)

Chemical stability of vanadium boride with aluminum. 29
E. Kolawa, J. M. Molarius, W. Flick, C. W. Nieh, L. Tran, M.-A. Nicolet (Pasadena, CA, U.S.A.), F. C. T. So (San Jose, CA, U.S.A.) and J. C. S. Wei (Santa Clara, CA, U.S.A.)

Metallization for VLSI circuits

The deposition mechanisms and microstructures of tungsten films produced by silicon reduction of WF_6 37
H. L. Park, C. D. Park and J. S. Chun (Seoul, South Korea)

A comparison of the step coverage of aluminum coatings produced by two sputter magnetron systems and a dual-beam ion system 45
J. K. G. Panitz, B. L. Draper and R. M. Curlee (Albuquerque, NM, U.S.A.)

Reactive-ion-etch-compatible metallization for partially covered contact applications 55
J. G. Ryan, N. P. Marmillion, J. P. Fineman and D. P. Bouldin (Essex Junction, VT, U.S.A.)

Effect of encapsulation on the reaction between palladium and GaAs thin films 63
E. T.-S. Pan, A. Venezia, E. Kolawa, J. M. Molarius, M.-A. Nicolet (Pasadena, CA, U.S.A.), J. L. Tandon (Huntington Beach, CA, U.S.A.) and R. Ruiz (Pasadena, CA, U.S.A.)

Thin films used in packaging technology

Process technology for packing applications 69
F. J. Bresnock (East Hartford, CT, U.S.A.)

Coatings for strain compliance in plastic packages: opportunities and realities 83
K. R. Kinsman, B. Natarajan and C. A. Gealer (Chandler, AZ, U.S.A.)

Interface interactions relevant to packaging technology 97
C.-A. Chang (Yorktown Heights, NY, U.S.A.)

The reliability of integrated circuits protected with Ti–W/Au bumps. 113
P. J. Pokela, T. M. Pitkanen and R. Ahlroth (Espoo, Finland)

Focused electron and ion beam repair strategies for wafer-scale interconnections in thin film packaging 121
H. T. Lin, J. F. McDonald, J. C. Corelli, S. Balakrishnan and N. King (Troy, NY, U.S.A.)

New materials and emerging technologies

Characterization of HfB_x films deposited by r.f. diode and r.f. magnetron sputtering 131
W. Y. Lee, G. Olive, F. Sequeda, V. Deline, T. Huang, G. Gorman and D. W. Chung (San Jose, CA, U.S.A.)

Ceramic beams and thin film growth 139
J. I. Brand and D. R. Miller (La Jolla, CA, U.S.A.)

Nitrides of titanium, niobium, tantalum and molybdenum grown as thin films by the atomic layer epitaxy method 149
L. Hiltunen, M. Leskela, M. Makela, L. Niinisto, E. Nykanen and P. Soininen (Espoo, Finland)

$In_{0.30}Al_{0.70}As/In_{0.30}Ga_{0.70}As$ quasi-insulating gate strained-layer field effect transistors grown by molecular beam epitaxy 155
P. Chu, C. L. Lin and H. H. Wieder (La Jolla, CA, U.S.A.)

Synthesis and microstructure of high T_c superconductors

Thermally sprayed coatings of $YBa_2Cu_3O_{6+x}$ 163
P. McGinn, N. Jain (Notre Dame, IN, U.S.A.), V. Anand and D. Lee (Goshen, IN, U.S.A.)

Growth and properties of $YBa_2Cu_3O_{7-x}$ superconducting thin films 171
S. I. Shah, C. R. Fincher (Wilmington, DE, U.S.A.), M. W. Duch (Deepwater, NJ, U.S.A.), D. A. Beames, K. M. Unruh and C. P. Swann (Newark, DE, U.S.A.)

Effects of deposition conditons on the superconducting properties of r.f. and d.c. magnetron sputter-deposited $YBa_2Cu_3O_{7-x}$ films. 181
W. Y. Lee, J. Salem, V. Lee, C. T. Rettner, G. Gorman, R. Savoy, V. Deline and T. Huang (San Jose, CA, U.S.A.) and D. W. Chung (San Jose, CA, U.S.A.)

METHODS OF CHARACTERIZING COATINGS AND MODIFIED SURFACES

Surface and thin film analysis techniques

Analysis of TiN by charged particle beams: nuclear reaction analysis, nuclear reaction broadening and Rutherford backscattering 191
V. H. Rotberg (Ann Arbor, MI, U.S.A.), A. J. Perry, C. C. Strandberg (Troy, MI, U.S.A.) and G. Was (Ann Arbor, MI, U.S.A.)

An evaluation of four computer modelling programs for Rutherford backscattering spectrometry analysis of oxidized surfaces 201
J. Saulitis, G. R. Johnston and J. L. Cocking (Maribyrnong, Victoria, Australia)

Resonant low energy electrons and their impact on non-destructive depth profiling of thin film samples* 213
J. S. Zabinski and B. J. Tatarchuk (Auburn, AL, U.S.A.)

Chemical characterization of the deactivation and protection of FeTi thin films using complementary non-destructive techniques 225
J. H. Sanders and B. J. Tatarchuk (Auburn, AL, U.S.A.)

Microstructural characterization techniques

Structural changes induced by heating in electroless nickel–phosphorus alloys 235
Q. X. Mai (Houston, TX, U.S.A.), R. D. Daniels and H. B. Harpalani (Norman, OK, U.S.A.)

Plasma spraying of WO_3: structural characterization of the coatings 249
M. Ladouceur, J. P. Dodelet (Varennes, Quebec, Canada), L. Parent and S. Dallaire (Boucherville, Quebec, Canada)

Electrical insulating properties of r.f.-sputtered magnesia coatings 255
P. Vuoristo, J. Wahlroos, T. Mantyla and P. Kettunen (Tampere, Finland)

X-ray microfluorescence analyzer for multilayer metal films. 263
B. J. Cross and D. C. Wherry (San Carlos, CA, U.S.A.)

A transmission electron microscopy study on the crystallization of amorphous Ni–P electroless deposited coatings. 273
E. Ma, S. Luo and P. Li (Shanghai, China)

Structure and properties of ion sulphocarbonitrided coatings on several structural steels 281
B. Wang, X. Luan, Z. Li and J. Zhang (Xian, China)

Mechanical properties of films and coatings

Mechanical behavior of aluminum and Al–Cu(2%) thin films 291
F. R. Brotzen, C. T. Rosenmayer (Houston, TX, U.S.A.) and R. J. Gale (Dallas, TX, U.S.A.)

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* Recipient of the Bunshah Award for the best paper in its Symposium.

Microhardness and microstructure of ion-beam-sputtered, nitrogen-doped NiFe films 299
T. W. Wu, C. Hwang, J. Lo and P. Alexopoulos (San Jose, CA, U.S.A.)

Effects of neutral gas incorporation in molybdenum coatings produced by magnetron sputtering. 309
P. Bosland, J. Danroc, R. Gillet and L. Lombard (Grenoble, France)

Non-destructive characterization techniques

Variable angle spectroscopic ellipsometry: a non-destructive characterization technique for ultrathin and multilayer materials 317
J. A. Woollam, P. G. Snyder and M. C. Rost (Lincoln, NE, U.S.A.)

Simultaneous determination of dispersion relation and depth profile of thorium fluoride thin film by spectroscopic ellipsometry 325
S. Y. Kim and K. Vedam (University Park, PA, U.S.A.)

Microscopic bubble formation and collapse at liquid–solid interfaces during electrical powering of thin film structures 335
S. Matts Goho and T. E. Orlowski (Webster, NY, U.S.A.)

Optical second harmonic generation as a probe of interface composition and structure 345
J. C. Hamilton and R. J. Anderson (Livermore, CA, U.S.A.)

Slow positron annihilation spectroscopy of heterojunctions and homojunctions of GaAs-based semiconductor thin films 349
R. L. Frost, A. B. Dewald, J. P. Schaffer, A. Rohatgi (Atlanta, GA, U.S.A.), B. Nielsen and K. G. Lynn (Upton, NY, U.S.A.)

PROTECTIVE COATINGS FOR MAGNETIC AND OPTICAL THIN FILM MEDIA

Preparation and characterization of reactively sputtered silicon nitride thin films 359
S. K. Ghosh and T. K. Hatwar (Rochester, NY, U.S.A.)

The bond structures and properties of chemically vapour deposited amorphous SiC 367
Y. J. Park, Y. W. Park and J. S. Chun (Seoul, South Korea)

Wear of Co–Ni thin film magnetic recording tape against metallic and ceramic surfaces. 375
D. R. Srinivasan, D. T. Gawne (Uxbridge, U.K.) and J. L. S. Wales (Hayes, U.K.)

THICK AND THIN FILM CENSORS

Insert-mounted thin film sensors for real-time monitoring of tool conditions . 387
W. P. Robbins, B. Bischoff and S. Ramalingen (Minneapolis, MN, U.S.A.)

AUTHOR INDEX 397